

Harvatek Surface Mount Chip LED Data Sheet HT-E17C1BP

Official Product	Product: HT-E17C1BP	Data Sheet No.		
Tentative Product	*****	HT-E17C1BP Series		
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DISCLAIMER

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LIFE SUPPORT POLICY

HARVATEK's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of HARVATEK or HARVATEK INTERNATIONAL. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.

2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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Product Specifications

	Specification	Material	Quantity
lv	100lm typ. @500mA		
	220Im typ. @1000mA		
	Ta=25 ⁰ C, ±10%		
Correlated Color	6000К Тур. @200mA / Та=25 ⁰ С,		
Temperature	Tolerance x,y±0.01		
Vf	3.15V typ. @500mA		
	3.5V typ. @1000mA		
	Ta=25℃, ±0.1 V		
lr	≧500μA @ V ℝ=5V / Ta=25 ⁰C		
Resin	White	Silicone Resin	
Carrier tape	Per EIA 481-1A specs	Plastic Tape	1000pcs per reel
Reel	Per EIA 481-1A specs	Plastic Black	
Label	HT standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	HT standard	Paper	Non-specfied

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and

InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

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Label Specifications



Harvatek P/N:



Lot No.:

1 2	3	4	5	6	7	8	9	10
E 1	Α	1	Α	2	2	L	1	2
Code 1 2	Code 3	Code 4	Code 5	Code 6	Code 7	Code 8	Code 9	Code 10
	Mfg. Year	Mfg. Month	Mfg. Date	Consecuti	ve number		Special code	
Internal Tracing Code	2010-A 2011-B 2012-C 2013-D	1:Jan. 2:Feb. A:Oct. B:Nov. C:Dec.	1:A 2:B 3:C 26:Z 27:7 28:8 29:9 30:3 31:4	01-	-77		000~ZZZ	

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Luminous Intensity (Iv) Bin:

Rank Code	Symbol	Condition	Min.	Тур.	Max.	Unit
PU1			87.4	-	99.6	
PU2	ΦV	I _F =500mA	99.6	-	113.6	Im
PV1			113.6	-	129.5	

Rank Code	Symbol	Condition	Min.	Тур.	Max.	Unit
PX1			192	-	218.9	
PX2	ΦV	I _F =1000mA	218.9	-	249.6	lm
PY1			249.6	-	284.6	

Forward Voltage (V_F) Bin:

Rank Code	Symbol	Condition	Min.	Тур.	Max.	Unit
PD	V _F		2.79	-	3.03	
PE		L - 500 m A	3.03	-	3.27	
PF		IF-20011A	3.27	-	3.51	v
PG			3.51	-	3.75	

Rank Code	Symbol	Condition	Min.	Тур.	Max.	Unit
PE			3.03	-	3.27	
PF	V _F	I _F =1000mA	3.27	-	3.51	V
PG			3.51	-	3.75	

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Chromaticity Bin:

	Rank D0						Rank D0			
Х	0.3135	0.31	0.317	0.32		Х	0.31	0.306	0.314	0.317
Y	0.301	0.322	0.329	0.307		Y	0.322	0.347	0.353	0.329
		Pank						Pan	レロイ	
		INALIK						i tan		
Х	0.32	0.317	0.326	0.327	-	Х	0.317	0.314	0.325	0.326
X Y	0.32 0.307	0.317 0.329	0.326	0.327 0.313	-	X Y	0.317 0.329	0.314 0.353	0.325 0.362	0.326 0.337
X Y	0.32 0.307	0.317 0.329	0.326	0.327 0.313		X Y	0.317 0.329	0.314 0.353	0.325 0.362	0.326 0.337

	Rank F0							
Х	0.327 0.326 0.339 0.337							
Y	0.313 0.337 0.347 0.321							

	Rank F1							
Х	0.326 0.325 0.341 0.339							
Y	0.337 0.362 0.373 0.347							

Bin Code	Min.	Тур.	Max.	Unit	Condition
F0	5250	5500	5750		
F1	5250	5500	5750		
E0	5750	6000	6250	K	I _F =500mA
E1	5750	6000	6250	n.	I _F =1000mA
D0	6250	6500	6750		
D1	6250	6500	6750		

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Color Temperature Coordinates



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Product Characteristics

Absolute Maximum Ratings

Product	Emission Color	I _F (mA)	I _{FP} * (mA)	V _R (V)	T _{sol} (°C)	T _{OP} (⁰C)	T _{ST} (⁰C)
	\M/hita	200	500	F	260	20°Ca + 95°C	40°Ca+120°C
	vville	200	1000	5	200	-30 Caros C	-40 C-+120 C

* Condition for $I_{\mbox{\scriptsize FP}}$ is pulse of 1/10 duty and 0.1msec width

**Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product,

such operation can cause migration resulting in LED damage.

Electro-Optical Characteristics

								<u>(Ta 25 °C</u>
Product Cold	Emission	n VF(V)		VF(V) C		Color Tem	perature (CCT)	l*∨(lm)
	Color	I⊧(mA)	typ	max	Min	typ	max	Тур
	\A/bite	500	3.39	3.75	5250	-	6750	100
HI-EI/CIBP	white	1000	3.27	3.75	5250	-	6750	220

* Per NIST standards

Package Outline Dimension

Recommended Soldering Pattern for Reflow Soldering

Unit: mm Tolerance: +/-0.1



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Characteristic Curves for TW @500mA



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Characteristic Curves for TW @1000mA



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Packaging

Tape Dimension



HT-E17C1 2.28+/-0.05 1.85+/-0.05 0.95+/-0.05 1K	Part No.	Dim.A	Dim.B	Dim.C	Q'ty/Reel
	HT-E17C1	2.28+/-0.05	1.85+/-0.05	0.95+/-0.05	1K

Unit: mm



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Reel Dimension



Packing



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Precaution for Use

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- (1) The chips should not be used directly in any type of fluid such as water, oil, organic solvent, etc.
- (2) When the LEDs are illuminating, the maximum ambient temperature should be first considered before operation.
- (3) LEDs must be stored in a clean environment. A sealed container with a nitrogen atmosphere is necessary if the storage period is over 3 months after shipping.
- (4) The LEDs are recommended to be used within seven days after unpacked. In accordance with MSL 2a: After the bag is opened, devices that will be subjected to infrared reflow, vapor-phase reflow, or equivalent processing must be mounted within 672 hours at factory conditions of ≤30°C/60%RH.
- (5) The appearance and specifications of products may be modified for improvement. We will provide PCN for any change or improvement.
- (6) The LEDs are sensitive to the static electricity and surge. It is strongly recommended to use a grounded wrist band and anti-electrostatic glove when handling the LEDs. If a voltage over the absolute maximum rating is applied to LEDs, it will damage LEDs. Damaged LEDs will show some abnormal characteristics such as remarkable increase of leak current, lower turn-on voltage and getting unlit at low current.

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LEDs and Eye Safety:

In the 1993 edition of IEC-60825-1, LEDs were included: "Throughout this part 1 light emitting diodes (LED) are included whenever the word "laser" is used. "The CENELEC document EN 60825-1 contains all the technical content of the IEC standard.

The scope of the IEC standard status that "...products which are sold to other manufacturers for use as components of any system for subsequent sale are not subject to IEC 60825-1, since the final product will itself be subject to this standard. "Therefore, it is important to determine the Laser Safety Class of the final product. However, it is important that employees working with LEDs are trained to use them safely.

Most of the products containing LEDs will fall in either Class 1 or Class 2. A Class 1 label is optional. HT-E17C1BP is a Class 1 LED product.

If a label is not used, this description must be included in the information for the user.

Amendment 2 to IEC 60825-1 is expected to be published in January 2001. The CENELEC equivalent is expected to follow three months after the IEC publication. This document contains increased Class 1 and Class 2 limits, as well as the introduction of less restrictive Class 1M and Class 2M.

For the exact classification and further information, the IEC document can be used:

IEC-60825-1 ISBN 2-8318-4169-0

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Precaution of Application

Designing 1: Soldering Pattern

The dimensions of the recommended soldering pattern may not meet every user. Please confirm and study first before designing the soldering pattern in order to obtain the best performance of soldering. Recommended soldering pattern is listed below:



Designing 2: Circuit Layout



Designing 3: Max Rating

Any application should refer to the specifications of absolute maximum ratings.

Dry Pack

Any SMD optical device, like this chip LED, is **MOISTURE SENSITIVE device**. Avoid absorbing moisture at any time during transportation or storage. Every reel will be packaged in the moisture barrier anti-static bag (Specific bag material will depend upon customers" requirement or option). And the bag is well sealed before shipment.

By customer's requirement, we will put a humidity indicator in each moisture barrier anti-static bag before shipment.

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The package



Storage

It's recommended to store the products in the following conditions:

Humidity: 60 %RH Max.

Temperature: 5°C ~30°C (41°F~86°F)

- 1. Shelf life in sealed bag: 12 month at<40 oC and <90%RH. (Base on aluminum laminated moisture barrier bag.)
- 2. After the bag is opened, devices that will be subjected to infrared reflow, vapor-phase reflow, or equivalent processing must be:
 - 2.1 Mounted within 72 hours at factory conditions of \leq 30°C /60% RH, or
 - 2.2 Stored at \leq 20% RH with zip-lock sealed.

Baking

It's recommended to bake before soldering once the pack is unsealed open & re-sealed after 72 hours. The conditions are as followings:

60 \pm 3°C×(12~24hrs) and < 5% RH, taped reel type

100±3°C×(45min~1hr), bulk type

130±3°C×(15~30min), bulk type

Soldering

Manual soldering (We do not recommend this method strongly.)

Soldering wire: 63/37 Sn/Pb, flux contained.

To prevent cracking, please bake before manual soldering, if the device is subject to moisture.

Temperature at tip of soldering tool : 300 oC±5 oC Max.(25W)

It's banned to load any stress on the resin during soldering.

Soldering time: 3±1sec

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Reflow Soldering

- 1. Recommend soldering paste specifications:
- 2. Operating temp.: Above 220°C, 60sec
- 3. Peak temp.:260°C Max., 10sec Max.
- 4. Never take next process until the component is cooled down to room temperature after reflow.
- 5. The recommended reflow soldering profile (measuring on the surface of the LED terminal) is following:

Lead-free Solder



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Cleaning

The conditions of cleaning after soldering: An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended. TemperaturexTime: <50°Cx30sec, or <30°Cx3min Ultra sonic cleaning: < 15W/ bath; Bath volume: 1liter max. Curing: 100 oC max, <3min Do not contact with component on the assembly board.

Cautions of Pick and Place

It should be avoided to load stress on the resin during high temperature.

Avoid rubbing or scraping the resin by any object.

Electric-static may cause damage to the component. Please confirm that the equipment grounding well. Using an ionizer fan is recommended.

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Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial release		1.0	06-23-2013

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